

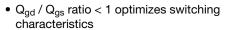
N-Channel 40 V (D-S) MOSFET



PRODUCT SUMMARY					
V _{DS} (V)	40				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00475				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 4.5 \text{ V}$	0.0067				
Q _g typ. (nC)	10.9				
I _D (A) ^a	78				
Configuration	Single				

FEATURES

- TrenchFET® Gen IV power MOSFET
- 100 ^% R_g and UIS tested

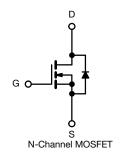




 Material categorization: for definitions of compliance please see www.vishav.com/doc?99912

APPLICATIONS

- Synchronous rectification
- High power density DC/DC
- DC/AC inverters



ORDERING INFORMATION	
Package	PowerPAK SO-8
Lead (Pb)-free and halogen-free	SiR4406DP-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	40		
Gate-source voltage		V _{GS}	+20, -16	V	
Continuous drain current (T _J = 150 °C)	T _C = 25 °C		78		
	T _C = 70 °C		62.4		
	T _A = 25 °C	I _D	21.3 ^{b, c}		
	T _A = 70 °C		17 ^{b, c}	A	
Pulsed drain current (t = 100 μs)		I _{DM}	200	^	
Continuous source-drain diode current	T _C = 25 °C	1	47.3		
	T _A = 25 °C	I _S	3.5 b, c		
Single pulse avalanche current	L = 0.1 mH	I _{AS}	20		
Single pulse avalanche energy	L = 0.1 IIII	E _{AS}	20	mJ	
Maximum power dissipation	$T_C = 25 ^{\circ}C$		41.6		
	T _C = 70 °C		26.6	W	
	T _A = 25 °C	P _D	3.9 b, c		
	T _A = 70 °C		2.5 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	°C	
Soldering recommendations (peak temperature) d, e		. 3	260	°C	

THERMAL RESISTANCE RATINGS						
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT	
Maximum junction-to-ambient b, f	t ≤ 10 s	R _{thJA}	23	32	°C/W	
Maximum junction-to-case (drain)	Steady state	R_{thJC}	2.4	3.0	C/VV	

Notes

- a. $T_C = 25 \,^{\circ}C$
- b. Surface mounted on 1" x 1" FR4 board
- t = 10 s

See solder profile (www.vishay.com/doc?73257). The PowerPAK SO-8 is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection

Rework conditions: manual soldering with a soldering iron is not recommended for leadless components

Maximum under steady state conditions is 70 °C/W

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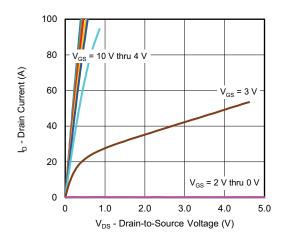
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static			•				
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40	-	-	V	
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 1 mA	-	29	-	>//00	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-4.5	-	mV/°C	
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250 \mu A$	1.1	-	2.4	V	
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = +20, -16 \text{ V}$	-	-	± 100	nA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V	-	-	1	1 .	
		V _{DS} = 40 V, V _{GS} = 0 V, T _J = 55 °C	-	-	10	μA	
Drain-source on-state resistance a	_	$V_{GS} = 10 \text{ V}, I_D = 15 \text{ A}$	-	0.00385	0.00475	Ω	
	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	0.0053	0.0067		
Forward transconductance a	9 _{fs}	$V_{DS} = 10 \text{ V}, I_D = 15 \text{ A}$	-	60	-	S	
Dynamic ^b			1		l .		
Input capacitance	C _{iss}		-	1851	-	pF	
Output capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$	-	326	-		
Reverse transfer capacitance	C _{rss}		-	26	-		
		V _{DS} = 20 V, V _{GS} = 10 V, I _D = 10 A	-	23.7	35.5		
Total gate charge	Qg		-	10.9	16.5		
Gate-source charge	Q _{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$	-	5.3	-	nC	
Gate-drain charge	Q _{qd}		-	1.9	-		
Output charge	Q _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}$	-	12	-		
Gate resistance	R_g	f = 1 MHz	1.4	2.8	4.7	Ω	
Turn-on delay time	t _{d(on)}		-	11	22		
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_L = 2 \Omega$	-	5	10	1	
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	22	44		
Fall time	t _f		-	6	12		
Turn-on delay time	t _{d(on)}		-	19	38	ns	
Rise time	t _r	$V_{DD} = 20 \text{ V}, R_1 = 2 \Omega$	-	50	100		
Turn-off delay time	t _{d(off)}	$I_D \cong 10 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$	-	22	44		
Fall time	t _f		-	9	18		
Drain-Source Body Diode Characteristic	s		1		l .		
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	47.3		
Pulse diode forward current ($t_p = 100 \mu s$)	I _{SM}		-	-	200	A	
Body diode voltage	V _{SD}	I _S = 5 A	-	0.75	1.1	V	
Body diode reverse recovery time	t _{rr}	-	-	22	44	ns	
Body diode reverse recovery charge	Q _{rr}	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s},$	-	9	18	nC	
Reverse recovery fall time	t _a	$T_J = 25 ^{\circ}\text{C}$	-	11	-		
-				1	 	ns	

Notes

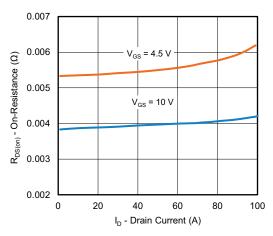
- a. Pulse test; pulse width $\leq 300~\mu s,~duty~cycle \leq 2~\%$
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

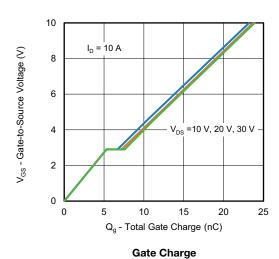


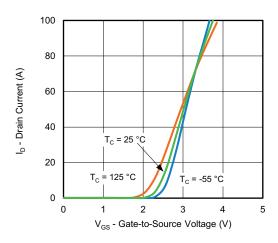


Output Characteristics

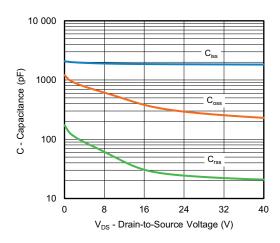


On-Resistance vs. Drain Current

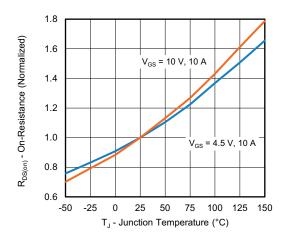




Transfer Characteristics

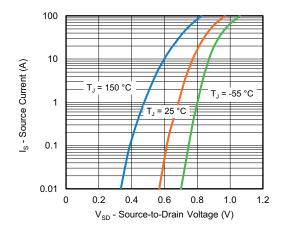


Capacitance

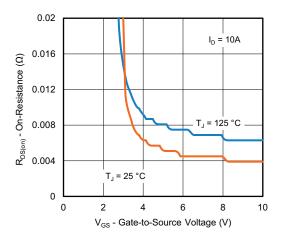


On-Resistance vs. Junction Temperature

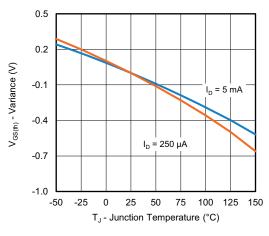




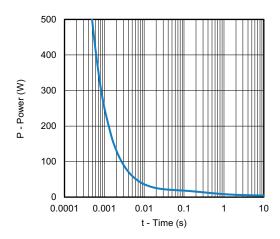
Source-Drain Diode Forward Voltage



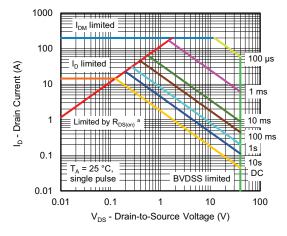
On-Resistance vs. Gate-to-Source Voltage



Threshold Voltage

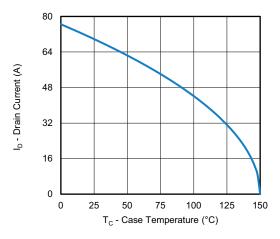


Single Pulse Power, Junction-to-Ambient

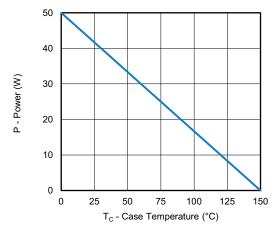


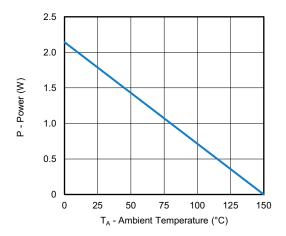
Safe Operating Area





Current Derating a





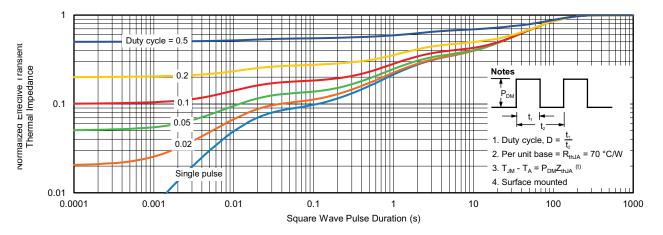
Power, Junction-to-Case

Power, Junction-to-Ambient

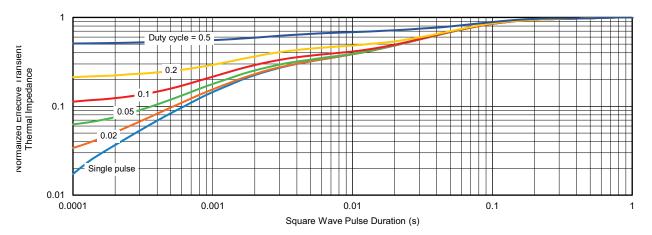
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit





Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

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